

## ABSTRACT

A polypropylene-based resin composition for metallized films, comprising (A) 100 parts by weight of a propylene random copolymer having an  $MFR_A$  of 1 to 30g/10 minutes, PI of 2.4 to 4, solubles contained at 20°C or lower at 1.5% by weight or less and solubles contained at 40°C or lower at 4.0% by weight or less, (B) 0.01 to 6 parts by weight of a polyethylene resin having a density of 0.945 to 0.980g/cm<sup>3</sup> and  $MI_B$  of 1 to 1000g/10 minutes, (C) 0.01 to 0.7 parts by weight of an antiblocking agent having an average particle size of 1.0 to 5.0 $\mu$ m and pore volume of 1.7mL/g or less, (D) 0.01 to 0.5 parts by weight of an antioxidant having a molecular weight of 500 or more and (E) 0.005 to 0.5 parts by weight of a hydrotalcite-based compound, and the metallized film of the same composition, excellent in processability, stiffness, heat-sealing property, resistance to blocking and surface scratching, containing a limited quantity of solubles, excellent in adhesion properties of the metallizing film to the base film, printability and lamination characteristics of the metallized surface.